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# **Supplementary Material**

## High performance Ag<sub>2</sub>Se film starting from a one-pot method for

### flexible thermoelectric Generator

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#### **Note S1: Experimental details**

#### **Materials**

Silver nitrate (AgNO<sub>3</sub>), selenium dioxide (SeO<sub>2</sub>), potassium hydroxide (KOH), potassium borohydride (KBH<sub>4</sub>) and ethanol were bought from Sinopharm Chemical Reagent Co., Ltd., China. 3-mercaptopropionic acid (MPA, HSCH<sub>2</sub>CH<sub>2</sub>COOH) was supplied by Aladdin Industrial Corporation. All the reagents were used directly without further purification. Porous nylon membrane with diameter of 50 mm and pore diameter of 0.22  $\mu$ m, was purchased from Haiyan Taoyuan Group. The deionized (DI) water used for all experiments was from a Flom ultrapure water system.

#### Synthesis of Ag<sub>2</sub>Se powders

In a typical procedure, 0.17 g AgNO<sub>3</sub>, 0.28 g KOH, 0.1 mL MPA, 0.11 g SeO<sub>2</sub> and 0.16 g KBH<sub>4</sub> were successively added into 100 mL deionized water under stirring. After reaction with stirring at room temperature (~25 °C), 40, 50, or 60 °C for 5 h, respectively, the products were collected and washed with water and ethanol for 3 times.

#### Preparation of Ag<sub>2</sub>Se films on nylon membrane

The as-prepared  $Ag_2Se$  powders were ultrasonically dispersed in ethanol to form a black dispersion solution. The  $Ag_2Se$  powders were then deposited on a porous nylon membrane through vacuum-assisted filtration to form a film. The prepared film was dried in a vacuum drying oven at 60 °C for 12 h. Finally, the  $Ag_2Se$  flexible TE film was obtained by hot-pressing at 230 °C and 1 MPa for 30min.

#### Note S2

#### Assembly of flexible TE generator (f-TEG)

A f-TEG consisting of six strips (20 mm  $\times$  5 mm) of the optimal film was assembled as follows: The two ends of each strip were coated with a thin layer of Au via evaporation to reduce contact resistance; the six strips were stuck on a polyimide (PI) substrate with an interval of 5 mm and then each strip was connected by Ag paste (SPI#04998-AB) in series.

#### Note S3

#### **Characterization and measurement**

The crystallinity and phase composition of the Ag<sub>2</sub>Se powders and Ag<sub>2</sub>Se films were examined by X-ray diffraction (XRD) (D/MAX2550VB3+/PCII). The morphologies were observed by scanning electron microscopy (SEM) and transmission electron microscopy (TEM). Field-emission scanning electron microscopy (FEI Nova NanoSEM 450) was used to examine the surface morphology of the Ag<sub>2</sub>Se NPs and Ag<sub>2</sub>Se films. Transmission electron microscope (TEM, Titan Themis G2 60-300, Thermo Fisher Scientific) was used to investigate the internal details of the film. The sample for TEM analysis was prepared by focused ion beam (FIB, Helios Nanolab G3 UC, Thermo Fisher Scientific). During the FIB processing, in order to avoid ion damage, a thin layer of Pt with thickness of around 2  $\mu$ m was firstly sputtered on the surface of the thin film with the gas injection system. A cross-sectional lamella beneath the Pt layer with size of 10  $\mu$ m × 5  $\mu$ m × 1  $\mu$ m was cut by high-energy Ga ion beams and was bonded to a post of copper lift-out grid with the FIB easy-lift system. The center area of the lamella was further thinned with low-energy Ga ion beams until the thickness was suitable for TEM observation. The contamination of Ga on the surface lamella was carefully removed after a shower of low-energy Ga ion beam.

The Seebeck coefficient (S) at RT was measured by the slope of the linear relationship between the thermal electromotive force and temperature difference between two ends on one side of each film. The electrical conductivity ( $\sigma$ ) at RT was measured using a four-probe technique. The temperature dependence TE properties of films were measured by a TE test system (Cryoall CTA-3) in He atmosphere, with an instrument test error of  $\pm 5\%$  for both  $\sigma$  and S. The Hall coefficient was measured by the Hall measurement system (LakeShore 8404). The in-plane thermal conductivity ( $\kappa$ ) was determined by the in-plane thermal diffusivity (D), the specific heat capacity (Cp) and the density ( $\rho$ ) of the film ( $\kappa = D \times C_p \times \rho$ ). The in-plane D was measured by a laser flash method (LFA467, NETZSCH). Cp was evaluated by a differential scanning calorimetry (DSC Q2000, TA), and the p was tested by measuring the mass and geometrical dimensions of the film. It is worth noting that the nylon film is not easy to separate and the contribution cannot be ignored, so the volume and mass involved in the thermal performance of the film test and calculation process includes the volume and mass of the nylon film.

The flexible test of the  $Ag_2Se$  film was performed by bending the film along 4 mm radius rod for fixed times and then the resistance of each bending was measured. The flexibility of the film is assessed by observing the difference between the resistance value after bending (R) and the initial resistance (R<sub>0</sub>).

For the output performance test of the f-TEG, all circuit components were connected

with conducting wires according to the circuit diagram shown in Fig. S19. In the TE generator, heat transfers from the hot side to the cold side along the length direction of the TE legs. We used an automatic temperature controlling system to heat a copper block and one end of the f-TEG was put on the copper block as the hot side (T +  $\Delta$ T). The other end of the f-TEG was put on an adiabatic foam acting as the cold side (T). The temperature of two ends was measured by two thermocouples. The f-TEG was connected as a generator into the circuit, which also includes a variable resistance box and an ammeter. Then we collected the output voltage and current by adjusting the variable resistance box at a particular temperature difference. The temperature difference was varied by setting different heating temperatures.

#### Note S4: Calculation details of the output performance of the f-TEG

The output power (P) is calculated by the following equation:

$$P = V_{out} \times I = \frac{V_{out}^2}{R_{ex} + R_{in}}$$

where  $V_{out}$  is the output voltage, I is the output current,  $R_{ex}$  is the external resistance, and  $R_{in}$  is the internal resistance of the f-TEG. When  $R_{ex}$  equals  $R_{in}$ , the maximum output power ( $P_{max}$ ) is obtained.

The maximum power density  $(PD_{max})$  is calculated using the following equation:

$$PD_{max} = \frac{P_{max}}{N \cdot A}$$

where N is the number of TE legs, and A is the cross-sectional area of the leg.

#### Note S5: Theoretical calculation details

We used the single parabolic band (SPB) model to calculate the Pisarenko curve, lattice thermal conductivity ( $\kappa_e$ ).

The solutions of the various transport properties in the SPB model involve integrals which are represented in terms of the "Fermi-Dirac" integral:

"Fermi-Dirac" integral

$$F_{i}(\eta) = \int_{0}^{\infty} f\varepsilon^{i} d\varepsilon = \int_{0}^{\infty} \frac{\varepsilon^{i}}{1 + exp(\varepsilon - \eta)} d\varepsilon$$

where  $F_i(\eta)$  is the Fermi integral of order *i*,  $\varepsilon$  represents the reduced energy (E/k<sub>B</sub>T) and  $\eta$  the reduced Fermi level (E<sub>F</sub>/k<sub>B</sub>T), *i* is the index of the integral, depends on both the transport property and energy dependence of the relaxation time of the charge carriers.

Within the SPB model, the transport parameters are expressed as follows: Seebeck coefficient (*S*)

$$S = \frac{k_B}{e} \left( \frac{2F_1(\eta)}{F_0(\eta)} - \eta \right)$$

Electrical conductivity ( $\sigma$ )

$$\sigma = n_H \mu_H e$$

Hall carrier concentration (n<sub>H</sub>)

$$n_{H} = \frac{4\pi}{r_{H}} \left( \frac{2m^{*}k_{B}T}{h^{2}} \right)^{3/2} F_{1/2}(\eta)$$

where  $m^*$  is the density of states effective mass,  $k_B$  is Boltzmann's constant, h is Planck's constant,  $r_H$  is the Hall factor for acoustic phonon scattering, which can be given by

$$r_{H} = \frac{3F_{1/2}(\eta)F_{-1/2}(\eta)}{4F_{0}^{2}(\eta)}$$

Lorenz number (*L*)

$$L = \left(\frac{k_B}{e}\right)^2 \frac{3F_0(\eta)F_2(\eta) - 4F_1^2(\eta)}{F_0^2(\eta)}$$

Electrical thermal conductivity ( $\kappa_e$ )

$$\kappa_e = L\sigma T$$

Lattice thermal conductivity ( $\kappa_l$ )

$$\kappa_l = \kappa - \kappa_e$$

# Note S6: Calculation details of the estimated value of output performance of the f-TEG

We estimated the open-circuit voltage, internal resistance, and output power based on the measured electrical conductivity and Seebeck coefficient, as detailed below:

The internal resistance  $(R_{in})$  consists of three parts: the resistance of six TE legs  $(R_a)$ , and Ag electrodes  $(R_b)$  and the contact resistance between the legs and Au layers and Ag electrodes  $(R_c)$ . Here,  $R_a$  can be calculated by the equation as follows:

$$R_a = N \frac{l}{\sigma \cdot \omega \cdot t}$$

where N is the number of TE legs,  $\sigma$  is the electrical conductivity of the film, l is the length,  $\omega$  is the width, and t is the thickness of the leg.

The open circuit voltage (V<sub>oc</sub>) can be estimated by the equation as follows:

$$V_{oc} = N \cdot |S| \cdot \Delta T$$

where N is the number of TE legs, S is the Seebeck efficient of the film, and  $\Delta T$  is the temperature difference.

The maximum output power  $(P_{max})$  can be estimated by the equation as follows:

$$P_{max} = \frac{V_{oc}^2}{4R_{in}} = \frac{(N \cdot S \cdot \Delta T)^2}{4N \frac{\iota}{\sigma A}} = N \cdot A \cdot \frac{S^2 \sigma}{4\iota} \cdot \Delta T^2$$

where A is the cross-sectional area of the leg,  $\boldsymbol{\sigma}$  is the electrical conductivity of the film.



Fig. S1. Schematic plot demonstrating preparation process of the  $Ag_2Se$  film on nylon

membrane.



Fig. S2. XRD patterns of the  $Ag_2Se$  films prepared from the  $Ag_2Se$  powders

synthesized at different temperatures for 5 h.



Fig. S3. SEM images of the Ag<sub>2</sub>Se powders: (a) 25-5P, (b) 40-5P, (c) 50-5P, (d) 60-

5P.



Fig. S4. Surface FESEM images of the Ag<sub>2</sub>Se films: (a-b) 25-5F, (c-d) 40-5F, (e-f)

50-5F, (g-h) 60-5F.

The morphology of 25-5F and 40-5F is different from that of 50-5F and 60-5F because the film surface before hot pressing is not absolutely smooth (this could be because the nylon membrane itself is not absolutely smooth and also the solution for filtering may be not very homogeneous). During hot pressing, thick places will contact the upper pressing head, while thinner places are not.



Fig. S5. TE parameters at RT of the Ag<sub>2</sub>Se films prepared from the Ag<sub>2</sub>Se powders

synthesized at different temperatures for 5 h.



Fig. S6. Cross-sectional SEM images of the 40-5F film.



Fig. S7. Cross-sectional SEM images of the Ag<sub>2</sub>Se films: (a) 25-5F, (b) 50-5F, (c) 60-

5F.



Fig. S8. Cross-sectional microstructure characterization of the 40-5F film. (a) Overview HAADF-TEM image. (b) HRTEM image of an area with some defects (denoted by dotted circles). (c) HRTEM image of an area with dislocations, inset is the corresponding IFFT image with some edge dislocations.



**Fig. S9.** Surface FESEM images of the Ag<sub>2</sub>Se films reported in: (a-b) Ref. 40 in the main manuscript, (c-d) Ref. 41 in the main manuscript, (e-f) this work.



Fig. S10. Cross-sectional SEM images of the Ag<sub>2</sub>Se films reported in: (a-b) Ref. 40 in

the main manuscript, (c-d) Ref. 41 in the main manuscript, (e-f) this work.



Fig. S11. HRTEM images of the Ag<sub>2</sub>Se film reported in Ref. 40 in the main

manuscript.



Fig. S12. TEM and HRTEM images of the  $Ag_2Se$  film reported in Ref. 41 in the main

manuscript.



Fig. S13. Hall carrier concentration dependence of Seebeck coefficient with estimated

DOS effective masses.



Fig. S14. Temperature dependence of (a) electrical conductivity, (b) Seebeck

coefficient of the 40-5F film for heating and cooling cycle.



Fig. S15. Temperature-dependent TE performance of two 40-5F samples prepared: (a) electrical conductivity, (b) Seebeck coefficient, (c) power factor.



Fig. S16. Flexibility test result of the 40-5F film (the bending radius is 4 mm).



Fig. S17. Surface FESEM images of the 40-5F film after bending for 1000 times with

a bending radius of 4 mm.



Fig. S18. Digital photographs of the nylon membrane on the back of the 40-5F film (1

 $\times$  1 cm²) (a) before and (b) after hot pressing.



Fig. S19. A schematic diagram for output performance measurement of the f-TEG.



Fig. S20. A digital photograph of the voltage generated from the f-TEG measured

with a multimeter without temperature difference.



Fig. S21. Performance of the six-leg f-TEG assembled with the 40-5F film: (a) Realtime open-circuit voltage (V<sub>oc</sub>) response to the applied  $\Delta T$ ; (b) Output power at  $\Delta T =$ 

10.1, 20.0, and 30.3 K as a function of load resistance.



**Fig. S22.** Digital photographs of internal resistance of the f-TEG at RT measured with a multimeter (a) before and (b) after being placed in air for 6 months.



Fig. S23. Comparison of the estimated and measured values of the (a) open circuit voltage ( $V_{oc}$ ) and (b) maximum output power ( $P_{max}$ ) under different  $\Delta T$ .

Method	Experimental procedure	Time (h)	Solvent	Total time (h)	Ref.
	Synthesis of Se NWs	4	DI water		[1-6]
	Washing of Se NWs	3	Ethanol, DI water		
	Growth of Se NWs	12	Ethanol		
Template	Drying of Se NWs	12	-	45	
	Dispersion of Se NWs	12	EG		
	Synthesis of Ag <sub>2</sub> Se	2	EG		
One-pot	Synthesis of Ag <sub>2</sub> Se	5	DI water	5	This work

**Table S1.** Comparison of two methods for synthesis of  $Ag_2Se$  powder.

 Table S2. Size distribution of some samples.

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Sample	Size
25-5P	$100 \sim 300 \text{ nm}$
40-5P	$100 \sim 500 \text{ nm}$
50-5P	$100\sim750~nm$
60-5P	$100 \sim 970 \text{ nm}$
25-5F	$700~nm \sim 4~\mu m$
40-5F	$600~nm \sim 6~\mu m$
50-5F	$1 \sim 7 \ \mu m$
60-5F	$1\sim 8 \ \mu m$

Number	n $(\times 10^{18} \text{ cm}^{-3})$	μ (cm <sup>2</sup> /Vs)	<i>S</i> (μV/K)	σ (S/cm)	PF (µW/mK <sup>2</sup> )	Ref.
1	4	870	-140.7	497	987.4±104.1	[1]
2	7.39	1024	-143	919.8	1882	[2]
3	5.08	1277	-150	908	2043	This work

Table S3. Comparison of TE parameters of the 40-5F film and previously reported

Ag<sub>2</sub>Se flexible TE films on nylon membranes (Ag<sub>2</sub>Se/nylon) at RT.

**Table S4.** Details of thermal property of the 40-5F film.

Temperatur e (K)	Density (g cm <sup>-3</sup> )	Specific heat capacity (J g <sup>-1</sup> K <sup>-1</sup> )	Thermal diffusivity (mm <sup>2</sup> s <sup>-1</sup> )	Thermal conductivity (W m <sup>-1</sup> K <sup>-1</sup> )
300	1.80	0.814	$0.534\pm0.002$	$0.782\pm0.003$
390	1.80	1.075	$0.521\pm0.001$	$1.008\pm0.001$

Materials	Methods	<i>S</i> (μV/K)	σ (S/cm)	PF (µW/mK <sup>2</sup> )	ZT	Ref.
$Ag_2Se/N^{\times}$	Template+VAF <sup>#</sup> +HP*	-140.7	497	987.4±104.1	0.6	[1]
$Ag_2Se/N^{st}$	Template+VAF <sup>#</sup> +HP*	-143	919.8	1882	0.8	[2]
Ag <sub>2</sub> Se/CuAgSe/Ag/N <sup>*</sup>	Template+VAF <sup>#</sup> +HP*	-45.5	7699	1593.9	0.4	[3]
Ag <sub>2</sub> Se/PVP/N*	Template+VAF <sup>#</sup> +HP*	-143.4	928	1910	1.1	[4]
$Ag/Ag_2Se/N^{\times}$	Template+VAF <sup>#</sup> +HP*	-67.5	3958	1860.6	-	[5]
PEDOT/Ag <sub>2</sub> Se/CuAgSe/N <sup>*</sup>	Template+VAF <sup>#</sup> +HP*	-121.8	1080	1603	0.6~1.05	[7]
Ag <sub>2</sub> Se/Ag/PEDOT/N*	Template+VAF <sup>#</sup> +HP*	-49.2	5957.3	1442.5	-	[8]
$Ag_2Se/Se/PPy/N$ *	Template+VAF <sup>#</sup> +HP*	-144	1064	2240	0.94	[6]
$Ag/Ag_2Se/N^{*}$	Microwave+VAF <sup>#</sup> +HP*	-98	3030	2436±240	-	[9]
Ag <sub>1.8</sub> Se/PI	vacuum thermal evaporation	-143	816	1700	-	[10]
S-doped $Ag_2Se/N^{*}$	Template+VAF <sup>#</sup> +HP*	-106	849	954.7	-	[11]
Ag <sub>2</sub> Se/PI	Sputtering+DMSER <sup>&amp;</sup>	-134	1440	2590±414	1.2±0.42	[12]
Bi <sub>2</sub> Te <sub>2.7</sub> Se <sub>0.3</sub> /PI	aerosol jet printing+sintering	-163.4	272	730	-	[13]
Bi <sub>2</sub> Te <sub>3</sub> /PI	Magnetron sputtering	-177.2	690	2170	-	[14]
$Ag_{0.005}Bi_{0.5}Sb_{1.5}Te_{3}/PI$	Magnetron sputtering	128.8	740	1240	-	[15]
Bi <sub>0.4</sub> Sb <sub>1.6</sub> Te <sub>3</sub> /Te/PI	Screen-printing+HP*	204	720.8	3000	1	[16]
Ag₂Se/N <sup>™</sup> (40-5F)	One-step solution+VAF <sup>#</sup> +HP*	-150	908	2043	0.8	This work

Table S5. Comparison of the room temperature TE properties of previously reported

flexible TE films and 40-5F film	1.
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\* N = Nylon, \* HP = Hot pressing, # VAF = Vacuum Assisted Filtration, & DMSER

= Direct Metal Surface Elemental Reaction.

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Materials	N	V <sub>oc</sub> (mV)	ΔT (K)	PD <sub>max</sub> (W m <sup>-2</sup> )	$\frac{PD_{max}I/\Delta T^2}{(\mu W m^{-1} K^{-2})}$	Ref.
Ag <sub>2</sub> Se/Nylon	4	18	30	2.3	51.11	[1]
Ag <sub>2</sub> Se/Nylon	4	18.5	30	22	488.89	[2]
Ag <sub>2</sub> Se/CuAgSe/Ag/Nylon	6	7.6	28	2.37	75.57	[3]
Ag <sub>2</sub> Se/PVP/Nylon	6	28.72	29.1	28.8	680.20	[4]
Ag/Ag <sub>2</sub> Se/Nylon	8	18	27	8.74	239.78	[5]
PEDOT/Ag <sub>2</sub> Se/CuAgSe/Nylon	11	35.7	29	6.4	190.25	[7]
Ag <sub>2</sub> Se/Ag/PEDOT/Nylon	4	5.6	27	7.47	204.94	[8]
Ag <sub>2</sub> Se/Se/PPy/Nylon	6	21.2	34.1	37.6	646.71	[6]
Ag/Ag <sub>2</sub> Se/Nylon	6	16.1	29.6	13.51	308.39	[9]
Ag <sub>1.8</sub> Se/PI	4	16.5	30	16.4	455.56	[10]
S-doped Ag <sub>2</sub> Se/Nylon	6	23	38.7	14.8	197.64	[11]
Ag <sub>2</sub> Se/PI	4	16.8	30	27.6±1.95	429.33	[12]
Ag <sub>2</sub> Se/Nylon	6	27.34	30.3	30.46	663.55	This work

**Table S6.** Comparison of the output properties of some previously reported  $Ag_2Se$ -based f-TEGs and the present f-TEG.

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